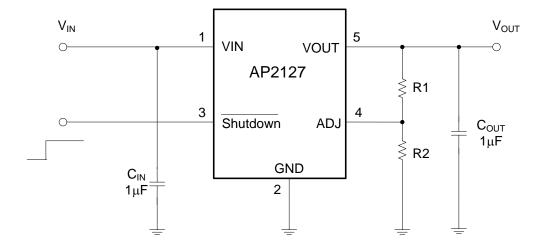
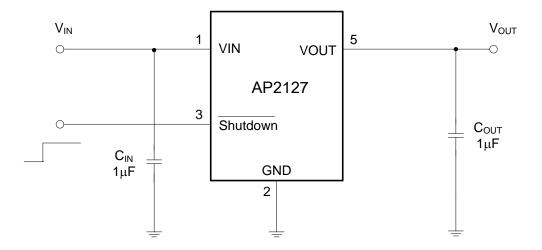


Typical Applications Circuit



 $V_{OUT} = 0.8(1+R1/R2)V$



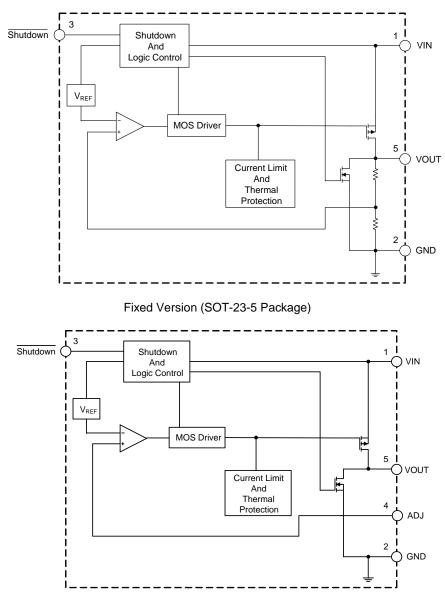
For Fixed Voltage Versions

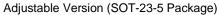


Pin Descriptions

Pin		Pin Number		
Name	SOT-23 SOT-23-3	SOT-23-5	SOT-89 (Option 1)	Function
VIN	3	1	2	Power Input
VOUT	2	5	3	Power Output
GND	1	2	1	Ground
NC/ADJ		4	—	No Connection / VOUT feedback input, connect resistor divider.
Shutdown		3	—	Enable Input.
PAD	—	_	—	Exposed PAD for thermal performance improvement connect to GND

Functional Block Diagram







Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Value		Unit
V _{IN}	Input Voltage	6.5		V
V _{CE}	Shutdown Input Voltage	-0.3 to V _{IN}	+0.3	V
lout	Output Current	450		mA
TJ	Junction Temperature	+150		°C
T _{STG}	Storage Temperature Range	-65 to +150		°C
T _{LEAD}	Lead Temperature (Soldering, 10sec)	+260		°C
		SOT-23	180	
0	Thermal Resistance	SOT-23-3	250	°C/W
θյΑ	(Junction to Ambient)	SOT-23-5	250	·C/W
		SOT-89 (Option 1)	100	
ESD	ESD (Human Body Model)	6000		V
ESD	ESD (Machine Model)	200		V

Note: 4. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Мах	Unit
V _{IN}	Input Voltage	2.5	6	V
T _A	Operating Ambient Temperature Range	-40	+85	°C

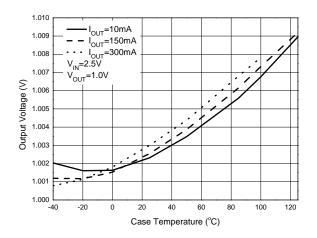


Electrical Characteristics (V_{IN} = 2.5V (for 0.8V to 1.8V voltage versions), V_{IN} = V_{OUT} +1V (for 2.5V to 4.75V voltage versions), V_{IN} = 6V @ V_{OUT} = 4.75V, T_A = +25°C, C_{IN} = 1 μ F, C_{OUT} = 1 μ F, Bold typeface applies over -40°C ≤ T_A ≤ +85°C, unless otherwise specified.)

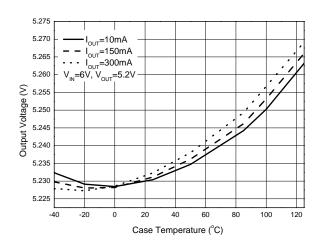
Symbol	Parameter	Condi	tions	Min	Тур	Max	Unit
V _{REF}	Reference Voltage	$V_{IN} = V_{OUT} + 1V$ 1mA ≤ I _{OUT} ≤ 300mA		0.784	0.8	0.816	V
Vout	Output Voltage	$V_{IN} = V_{OUT} + 1V$ 1mA $\leq I_{OUT} \leq 300$ mA		98% x Vout	_	102% х V _{OUT}	V
V _{IN}	Input Voltage	_		2.5	_	6	V
IOUT(MAX)	Maximum Output Current	V _{IN} - V _{OUT} = 1V V _{OUT} = 0.98 x V _{OUT}		300	400	_	mA
ΔVουτ	Load Regulation	$V_{IN} - V_{OUT} = 1V$ 1mA $\leq I_{OUT} \leq 300$ mA	_	4	10	mV	
ΔV _{OUT}	Line Regulation	$V_{OUT} + 0.5V \le V_{IN} \le 6V$ $I_{OUT} = 30 \text{mA}$		_	0.5	5	mV
		V _{OUT} = 1.0V, I _{OUT} = 3	300mA	_	1400	1500	
		V _{OUT} = 1.2V, I _{OUT} = 3		_	1200	1300	
		V _{OUT} = 1.5V, I _{OUT} = 3		_	900	1000	
	Dropout Voltogo	Vout = 1.8V, lout = 3		_	600	700	
V _{DROP}	Dropout Voltage		V _{OUT} = 2.5V, 2.8V, 3.0V, 3.3V, 4.2V,		170	300	mV
		V _{OUT} = 4.75V, I _{OUT} = 300mA		-	140	300	
lq	Quiescent Current	$V_{IN} = V_{OUT} + 1V$, $I_{OUT} = 0mA$		—	60	90	μA
I _{STD}	Standby Current	V _{IN} = V _{OUT} +1V V _{SHUTDOWN} in off mode		_	0.1	1.0	μA
		AP2127-1.0V to	f = 100Hz	_	68	_	dB
	Power Supply Rejection Ration	4.2V, Ripple 1V _{P-P}	f = 1kHz	—	68	_	dB
PSRR		$V_{IN} = V_{OUT} + 1V$	f = 10kHz	_	54		dB
1 OKK		AP2127-4.75V,	f = 100Hz		63	—	dB
		Ripple 0.5V _{P-P}	f = 1kHz		63	—	dB
		$V_{IN} = V_{OUT} + 1V$	f = 10kHz	—	45	—	dB
ΔV _{OUT} /V _{OUT} /ΔT	Output Voltage Temperature Coefficient	I _{OUT} = 30mA, -40°C ≤	≤ T _A ≤ +85°C		±100	—	ppm/s
I _{SHORT}	Short Current Limit	$V_{OUT} = 0V$		—	50	—	mA
t _{SS}	Soft Start Time	-		_	50		μs
V _{NOISE}	RMS Output Noise	$T_A = +25^{\circ}C$, $10Hz \le f$ $V_{OUT} = 0.8V$	⁻ ≤ 100kHz,	-	60	_	μV _{RM}
_	Shutdown High Voltage	Shutdown Input Volta	age High	1.5	_	_	V
_	Shutdown Low Voltage	Shutdown Input Volta	age Low	—	_	0.5	V
—	V _{OUT} Discharge MOSFET R _{DS(ON)}	Shutdown Input Voltage Low		—	60	_	Ω
_	Shutdown Pull Down Resistance	_		_	3	_	MΩ
	Thermal Shutdown			—	+165	—	°C
_	Thermal Shutdown Hysteresis	—		—	+30	—	Ŭ
		SOT-23			100	—	
θις	Thermal Resistance	SOT-23-3		—	150	—	°C/W
-00		SOT-23-5		150	—		
		SOT-89 (Option 1)		—	75	_	

Performance Characteristics (Note 5)

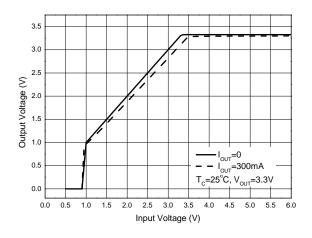
Output Voltage vs. Case Temperature



Output Voltage vs. Case Temperature

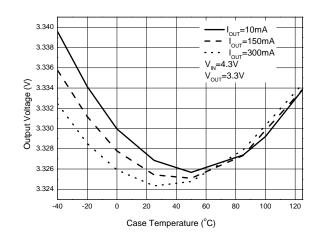


Output Voltage vs. Input Voltage

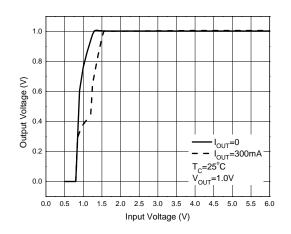


Note 5: Maximum output of 4.75V passed qualification test. Performance Characteristics for 5.2V are for reference only.

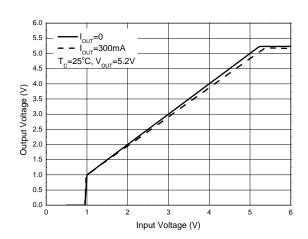
Output Voltage vs. Case Temperature



Output Voltage vs. Input Voltage

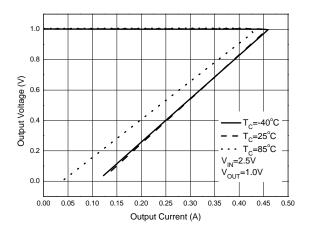


Output Voltage vs. Input Voltage

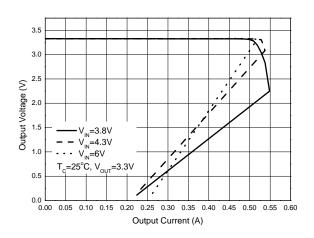




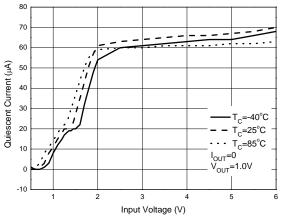
Output Voltage vs. Output Current



Output Voltage vs. Output Current

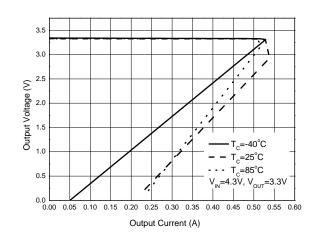


Quiescent Current vs. Input Voltage

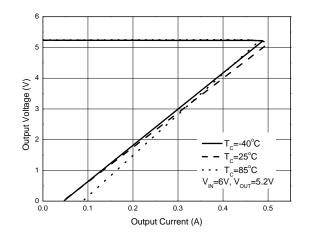


Maximum output of 4.75V passed qualification test. Performance Characteristics for 5.2V are for reference only. Note 5:

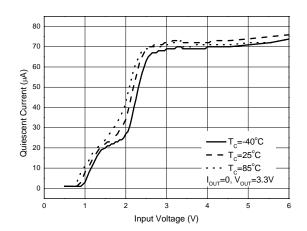
Output Voltage vs. Output Current



Output Voltage vs. Output Current

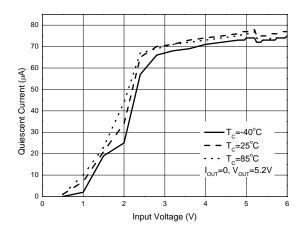


Quiescent Current vs. Input Voltage

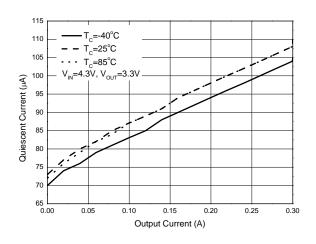




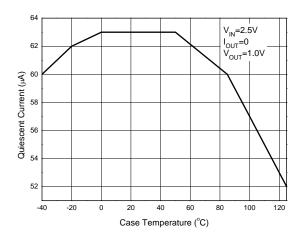
Quiescent Current vs. Input Voltage



Quiescent Current vs. Output Current

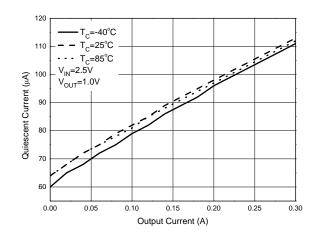


Quiescent Current vs. Case Temperature

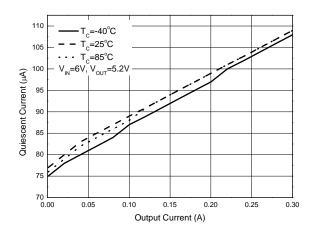


Note 5: Maximum output of 4.75V passed qualification test. Performance Characteristics for 5.2V are for reference only.

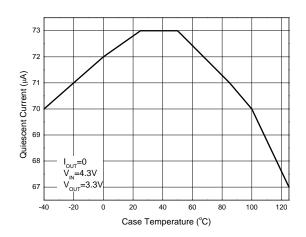
Quiescent Current vs. Output Current



Quiescent Current vs. Output Current



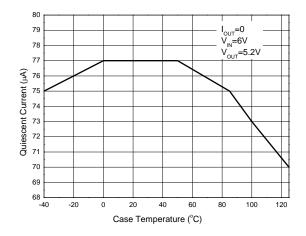
Quiescent Current vs. Case Temperature



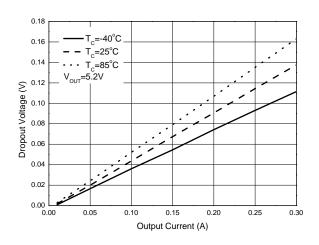
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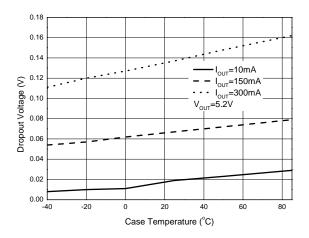
Quiescent Current vs. Case Temperature



Dropout Voltage vs. Output Current

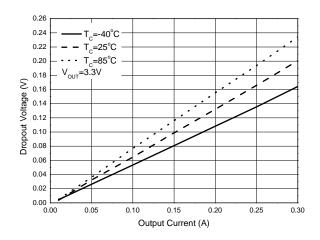


Dropout Voltage vs. Case Temperature

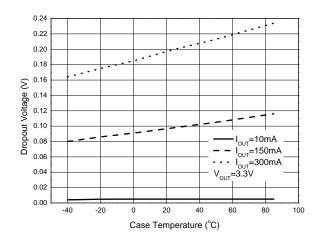


Note 5: Maximum output of 4.75V passed qualification test. Performance Characteristics for 5.2V are for reference only.

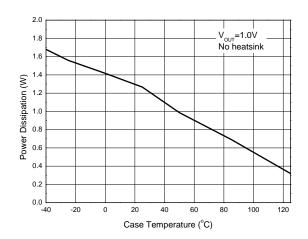
Dropout Voltage vs. Output Current



Dropout Voltage vs. Case Temperature

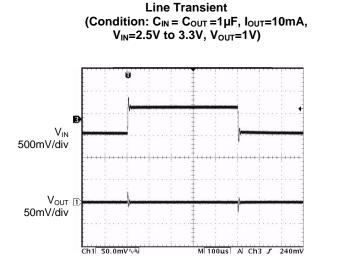


Power Dissipation vs. Case Temperature

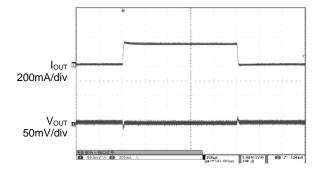


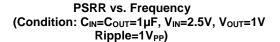
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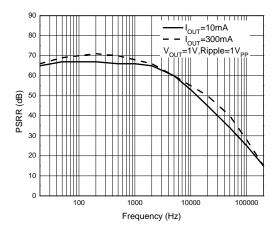




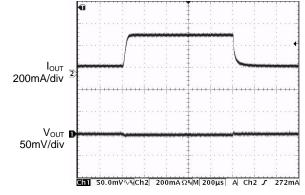
 $\begin{array}{c} Load \mbox{ Transient} \\ \mbox{(Condition: } C_{\text{IN}}=C_{\text{OUT}}=1 \mu F, \mbox{ } I_{\text{OUT}}=10 m A \mbox{ to } 300 m A, \\ V_{\text{IN}}=4.3 V, \mbox{ } V_{\text{OUT}}=3.3 V) \end{array}$



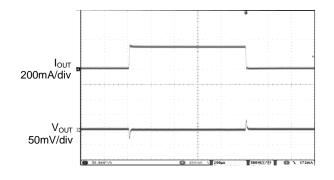




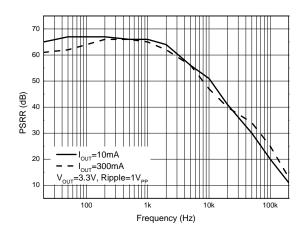
Load Transient (Condition: C_{IN}=C_{OUT}=1µF, Slew Rate=20mA/µs, V_{IN}=2.5V, V_{OUT}=1V, I_{OUT}=10mA to 300mA)



 $\label{eq:load-transient} \begin{array}{l} Load Transient \\ (Condition: C_{IN}=C_{OUT}=1 \mu F, Slew Rate=20 mA/\mu s, \\ V_{IN}=6V, V_{OUT}=5.2V, I_{OUT}=10 mA to 300 mA) \end{array}$



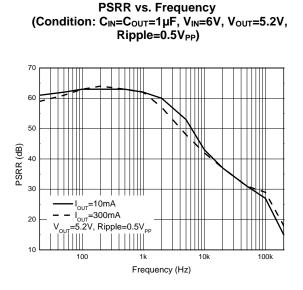
PSRR vs. Frequency (Condition: C_{IN}=C_{OUT}=1μF, V_{IN}=4.3V, V_{OUT}=3.3V, Ripple=1V_{PP})



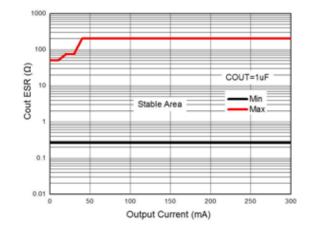
Note 5: Maximum output of 4.75V passed qualification test. Performance Characteristics for 5.2V are for reference only.

AP2127 Document number: DS36478 Rev. 6 - 2 Downloaded from Arrow.com.

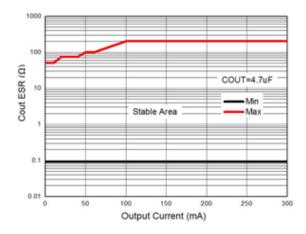




Region of Stable C_{OUT} ESR vs. Output Current (C_{OUT} = 1µF)



Region of Stable C_{OUT} ESR vs. Output Current ($C_{OUT} = 4.7 \mu F$)



Note 5: Maximum output of 4.75V passed qualification test. Performance Characteristics for 5.2V are for reference only.



Application Notes

Input Capacitor

A 1µF ceramic capacitor is recommended to connect between VIN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both V_{IN} and GND.

Output Capacitor

The output capacitor is required to stabilize and help transient response for LDO. The AP2127 is stable with very small ceramic output capacitor with a low ESR 1µF or higher of X7R or X5R MLCC capacitor, which will be sufficient at full temperature ranges. Additional capacitance helps to reduce undershoot and overshoot during transient. Place output capacitor as close as possible to VOUT and GND pins, and keep the leads as short as possible.

Adjustable Operation

For adjustable version, the output voltage is calculated by:

$$V_{OUT} = V_{REF} \left(1 + \frac{R_1}{R_2} \right)$$

Where $V_{REF} = 0.8V$ (the internal reference voltage)

Rearranging the equation will give the following that is used for adjusting the output to a particular voltage:

$$R_1 = R_2 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right)$$

For AP2127, the resistor at the low side (R₂) can be selected from $5k\Omega$ to $200k\Omega$.

In order to improve the stability and to decrease the noise level of the adjustable version, a feed-forward capacitor is suggested to be placed between VOUT and ADJ pins (Figure 1). It's recommended that this feed-forward capacitor value can be calculated as:

$$0.7kHz \!\leq\! \frac{1}{2\pi \!\times\! R_1 \!\times\! C_{ff}} \!\leq\! 15kHz$$

The recommended value of the feed-forward capacitor for different resistor divider ratios is shown in the table below.

Output Voltage	R1	R2	C _{ff}
1.2V	7.5kΩ	15kΩ	2.7nF
1.6V	7.5kΩ	7.5kΩ	2.7nF
1.8V	22.5kΩ	18kΩ	1nF
1.9V	7.5kΩ	5.49kΩ	2.7nF
2.5V	38.3kΩ	18kΩ	560pF
3.3V	56.2kΩ	18kΩ	390pF
4.0V	120kΩ	30.1kΩ	180pF

Table 1. Output Voltage Setting Guide

AP2127



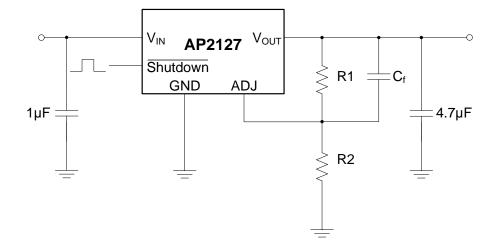


Figure 1. Application Circuit with Feed-forward Capacitor

Current Limit Protection

When output current at VOUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to prevent over-current and to protect the regulator and load from damaged due to overheating.

Short Circuit Protection

When VOUT pin is shorted to GND, short circuit protection will be triggered and clamp the output current to approximately 50mA.

Auto discharge with Shutdown Version

For shutdown version, an auto discharge MOSFET with $R_{DS(ON)}$ of 60 Ω typical is integrated between VOUT and GND pins, which can discharge the charge of the output capacitors quickly when turning off AP2127 with Shutdown pin.

Thermal Consideration

Internal thermal protection circuitry of AP2127 is used to protect device during overload conditions. For continuous operation, ensure not to exceed the operating junction temperature range of +125°C.

The power dissipation definition in the device is:

 $P_{D} = (V_{IN} - V_{OUT}) \times I_{OUT} + V_{IN} \times I_{Q}$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout and the surrounding airflow. The maximum power dissipation can also be calculated as:

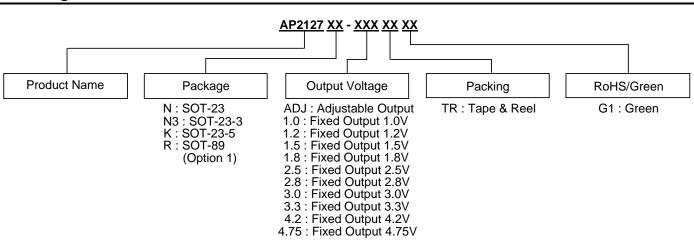
 $\mathsf{P}_{\mathsf{D}(\mathsf{MAX})} = \left(\mathsf{T}_{\mathsf{J}(\mathsf{MAX})} - \mathsf{T}_{\mathsf{A}}\right) / \, \theta_{\mathsf{J}\mathsf{A}}$

The maximum power dissipation for SOT-23-5 package (least copper size) at T_A = +25°C can be calculated as:

 $P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C) / (250^{\circ}C/W) = 0.4W$



Ordering Information

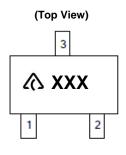


Part Number	Marking ID	Temperature Range	Package	Packaging
AP2127N-1.0TRG1	GU8			3000/Tape & Reel
AP2127N-1.2TRG1	GS8			3000/Tape & Reel
AP2127N-1.5TRG1	GV8			3000/Tape & Reel
AP2127N-1.8TRG1	GW8		SOT-23	3000/Tape & Reel
AP2127N-2.5TRG1	GT9		301-23	3000/Tape & Reel
AP2127N-2.8TRG1	GU9			3000/Tape & Reel
AP2127N-3.0TRG1	GV9	-40°C to +85°C		3000/Tape & Reel
AP2127N-3.3TRG1	GW9			3000/Tape & Reel
AP2127N3-1.2TRG1	GU2		SOT-23-3	3000/Tape & Reel
AP2127N3-1.5TRG1	GU3		501-23-3	3000/Tape & Reel
AP2127K-ADJTRG1	GEH			3000/Tape & Reel
AP2127K-1.0TRG1	GEG	-40°C to +85°C		3000/Tape & Reel
AP2127K-1.2TRG1	GEI			3000/Tape & Reel
AP2127K-1.5TRG1	GEP			3000/Tape & Reel
AP2127K-1.8TRG1	GEQ			3000/Tape & Reel
AP2127K-2.5TRG1	GER		SOT-23-5	3000/Tape & Reel
AP2127K-2.8TRG1	GES			3000/Tape & Reel
AP2127K-3.0TRG1	GHF			3000/Tape & Reel
AP2127K-3.3TRG1	GET			3000/Tape & Reel
AP2127K-4.2TRG1	GEU			3000/Tape & Reel
AP2127K-4.75TRG1	GEZ			3000/Tape & Reel
AP2127R-3.3TRG1	G42P		SOT-89 (Option 1)	1000/Tape & Reel



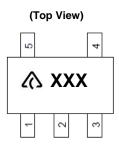
Marking Information

(1) SOT-23, SOT-23-3



XXX: Marking ID (See Ordering Information)

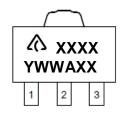
(2) SOT-23-5



XXX: Marking ID (See Ordering Information)

(3) SOT-89 (Option 1)

(Top View)

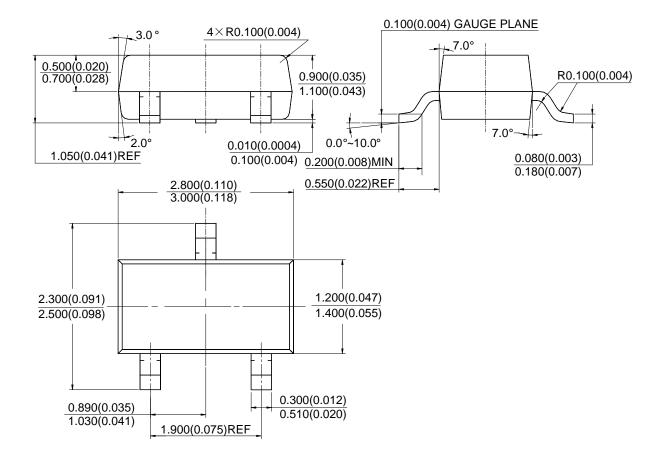


First Line: Logo and Marking ID (See Ordering Information) Second Line: Date Code Y: Year WW: Work Week of Molding A: Assembly House Code XX: 7th and 8th Digits of Batch Number



Package Outline Dimensions (All dimensions in mm.)

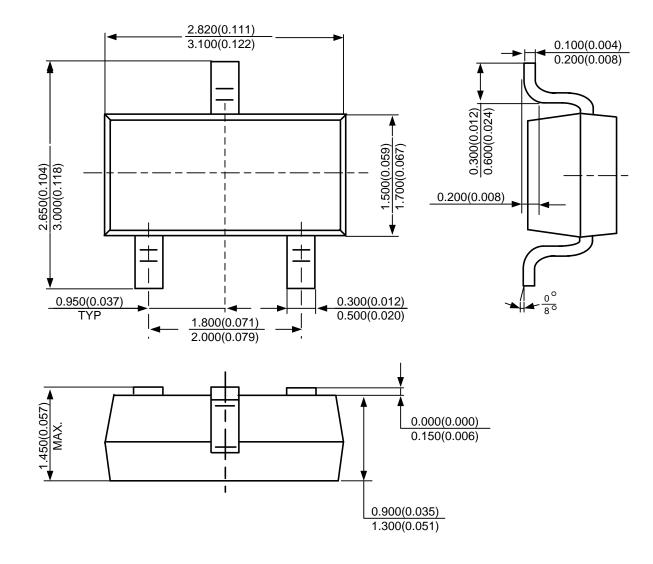
(1) Package Type: SOT-23





Package Outline Dimensions (Cont.) (All dimensions in mm.)

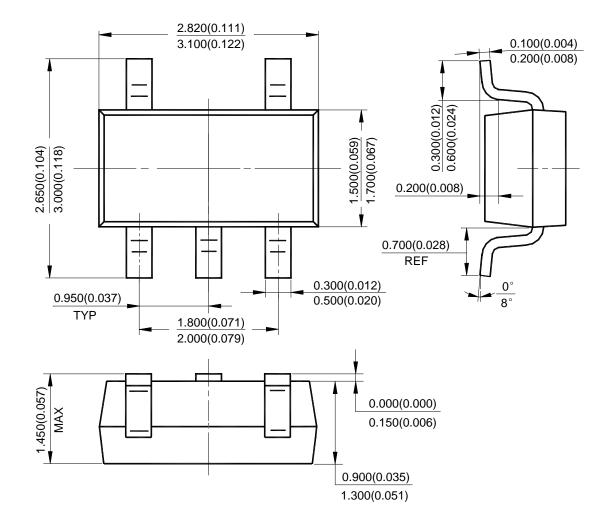
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Package Outline Dimensions (Cont.) (All dimensions in mm.)

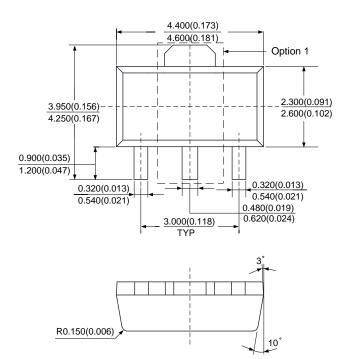
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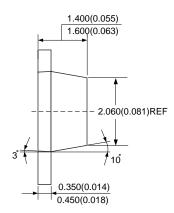




Package Outline Dimensions (Cont.) (All dimensions in mm.)

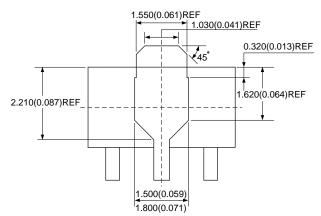
(4) Package Type: SOT-89

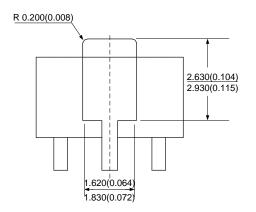




Option 1



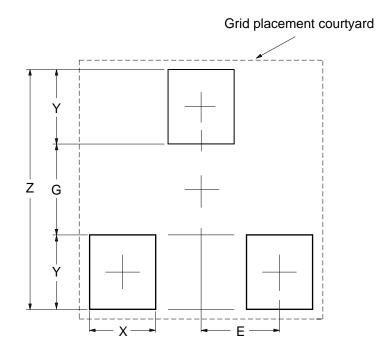






Suggested Pad Layout

(1) Package Type: SOT-23

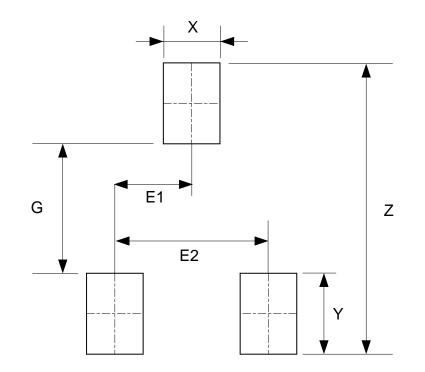


Dimensions	Z	G	X	Y	E
	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)
Value	2.900/0.114	1.100/0.043	0.800/0.031	0.900/0.035	0.950/0.037



Suggested Pad Layout (Cont.)

(2) Package Type: SOT-23-3

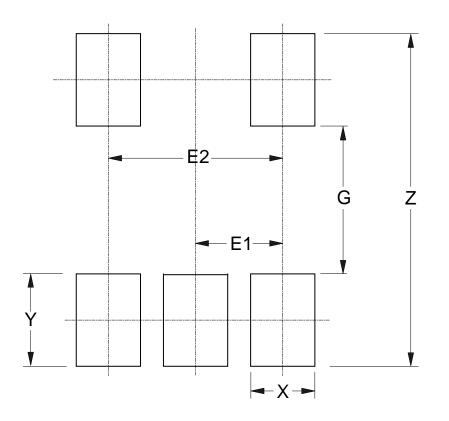


Dimensions	Z	G	Х	Y	E1	E2
	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)
Value	3.600/0.142	1.600/0.063	0.700/0.028	1.000/0.039	0.950/0.037	1.900/0.075



Suggested Pad Layout (Cont.)

(3) Package Type: SOT-23-5

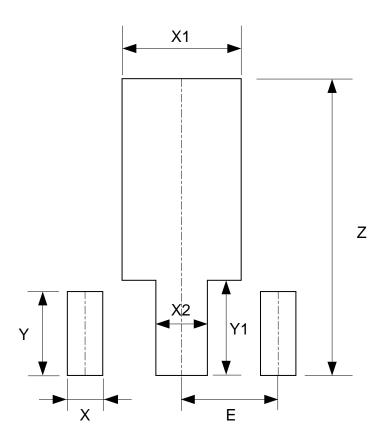


Dimensions	Z	G	Х	Y	E1	E2
	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)	(mm)/(inch)
Value	3.600/0.142	1.600/0.063	0.700/0.028	1.000/0.039	0.950/0.037	1.900/0.075



Suggested Pad Layout (Cont.)

(4) Package Type: SOT-89



Dimensions	Z	Х	X1	X2	Y	Y1	E
	(mm)/(inch)						
Value	4.600/0.181	0.550/0.022	1.850/0.073	0.800/0.031	1.300/0.051	1.475/0.058	1.500/0.059



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